

Part Number: XZMG55W-3

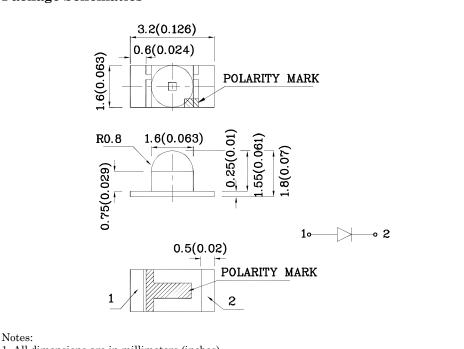
3.2x1.6mm SMD CHIP LED LAMP

Features

- Ideal for indication light on hand held products
- Long life and robust package
- Variety of lens types and color choices available
- Package: 2000 pcs / reel
- Moisture sensitivity level : level 3
- RoHS compliant







1. All dimensions are in millimeters (inches).

2. Tolerance is $\pm 0.2(0.008")$ unless otherwise noted.

3. Specifications are subject to change without notice.

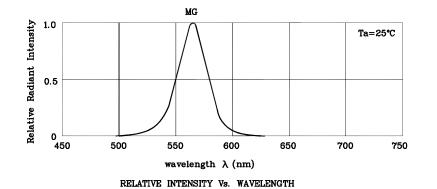
Absolute Maximum Ratings (T _A =25°C)		MG (GaP)	Unit	
Reverse Voltage	V_{R}	5	V	
Forward Current	$I_{\rm F}$	25	mA	
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	$i_{\rm FS}$	140	mA	
Power Dissipation	P_{D}	62.5	mW	
Operating Temperature	$T_{\rm A}$	-40 ~ +85	°C	
Storage Temperature	Tstg	-40 ~ +85	-0	

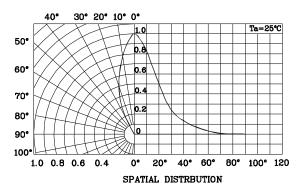
Operating Characteristics (T _A =25°C)		MG (GaP)	Unit	
Forward Voltage (Typ.) (I _F =20mA)	V_{F}	2.2	V	
Forward Voltage (Max.) (I _F =20mA)	V_{F}	2.5	V	
Reverse Current (Max.) (V _R =5V)	I_R	10	uA	
Wavelength of Peak Emission (Typ.) (I _F =20mA)	λP	565	nm	
Wavelength of Dominant Emission (Typ.) (I _F =20mA)	λD	568	nm	
Spectral Line Full Width At Half-Maximum (Typ.) (I _F =20mA)	$ riangle\lambda$	30	nm	
Capacitance (Typ.) (V _F =0V, f=1MHz)	С	15	$_{\rm pF}$	

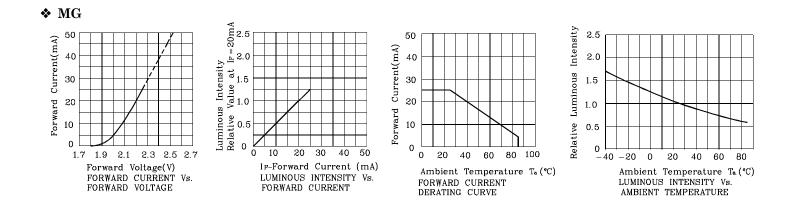
min. typ. XZMG55W-3 Green GaP Water Clear 30 54 565 4	Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity (I _F =20mA) mcd		Wavelength nm λP	Viewing Angle 20 1/2
XZMG55W-3 Green GaP Water Clear 30 54 565 4					min.	typ.		
	XZMG55W-3	Green	GaP	Water Clear	30	54	565	40°

P. 1/4









LED is recommended for reflow soldering and soldering profile is shown below.

Reflow Soldering Profile for SMD Products (Pb-Free Components)

300 (°C) 10 s max 250 4°C/s C/s max 200 150~180 4°C/s max 150 Temperature 30~50s 80~120: 100 50 0 150 0 50 100 200 250 300 (sec) Time Notes: 1. Maximum soldering temperature should not exceed 260°C

Maximum soldering temperature should not exceed 200%
Recommended reflow temperature: 145°C-260°C

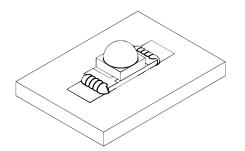
3. Do not put stress to the epoxy resin during

high temperatures conditions

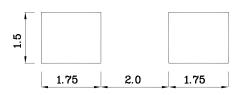
P. 2/4



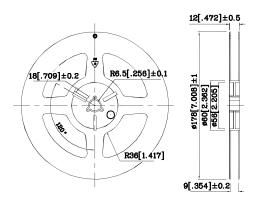
✤ The device has a single mounting surface. The device must be mounted according to the specifications.



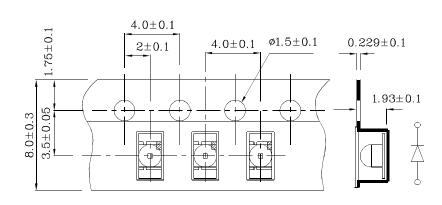
Recommended Soldering Pattern (Units : mm; Tolerance: ± 0.1)



Reel Dimension



Tape Specification (Units : mm)



TAPE

Remarks:

If special sorting is required (e.g. binning based on forward voltage, Luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm

2. Luminous intensity / luminous flux: +/-15\%

3. Forward Voltage: +/-0.1V $\,$

Note: Accuracy may depend on the sorting parameters.

Apr 18,2011



PACKING & LABEL SPECIFICATIONS

